

29/11/02
2002073021



162162

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
14 November 2002 (14.11.2002)

PCT

(10) International Publication Number
WO 02/090434 A1

(51) International Patent Classification⁷: C08L 63/00,
C08K 5/5399, C08L 85/02

(21) International Application Number: PCT/JP01/10139

(22) International Filing Date:
20 November 2001 (20.11.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2001-123798 23 April 2001 (23.04.2001) JP
2001-256172 27 August 2001 (27.08.2001) JP
2001-273216 10 September 2001 (10.09.2001) JP

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(81) Designated States (national): CN, KR, SG, US.

(84) Designated States (regional): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

WO 02/090434 A1

(54) Title: EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

(57) Abstract: The present invention provides an epoxy resin composition for encapsulation of semiconductors which contains substantially neither halogen-based flame retarding agents nor antimony compounds and is excellent in moldability, flame retardance, high-temperature storage characteristics, reliability for moisture resistance, and solder cracking resistance. That is, the present invention is an epoxy resin composition for encapsulating semiconductors which contains (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a phosphazene compound as essential components, the total weight of phosphate ion and phosphite ion contained in the phosphazene compound being not more than 500 ppm. Further, the epoxy resin composition may optionally contain a flame-retarding assistant or an ion scavenger.



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